

Editorial

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The Sixteenth IEEE International Mixed-Signals, Sensors, and Systems Test Workshop (IMS3TW) was held during June 2010 in Montpellier, France. Around that time we issued a call for papers for this special issue on Analog, Mixed-Signal, RF and MEMS Testing. Haralampos Stratigopoulos and Krishnendu Chakrabarty assumed responsibilities of being guest editors. From the papers received, fifteen were accepted and appear here representing a variety of topics. I would like to thank all authors who submitted their papers and reviewers who provided meaningful and timely evaluations. The guest editors deserve the most credit for pulling the whole effort together. This issue is lasting evidence of the unfailing devotion of these people.

Testing used to be mostly digital. But that role is changing because the shape of electronic systems is changing. The multichip modules, systems-on-chip and 3-D chips will combine digital, analog, radio frequency, electromechanical, fluidic, biological, chemical and who knows what devices. So we will be learning how to test each one of these devices as well as various combinations of them. That will be the true mixed-signal testing, not just the digital-analog mixture of the past.

As we go to press, the Seventeenth IEEE International Mixed-Signals, Sensors, and Systems Test Workshop is getting underway in Santa Barbara, California (May 16–18, 2011). Hopefully, we will have another special issue next year.

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